INTEGRATED CIRCUITS



Product data Supersedes data of 2002 Mar 15 2002 Oct 10



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PCK2002PL

FEATURES

- General purpose and PCI-X 1:4 clock buffer
- 8-pin TSSOP 3.1 × 4.4 mm package
- Same form, fit, and function as CDCV304
- See PCK2001P for 3.1 × 3.1 mm TSSOP-8 package
- See PCK2001 or PCK2002 for 48-pin 1:18 buffer part
- See PCK2001M ro PCK2002M for 28-pin 1:10 buffer part
- See PCK2001R for 16-pin 1:6 buffer part
- Operating frequency: 0 533 MHz
- Part-to-part skew < 500 ps
- Low output skew: <200 ps
- 3.3 V operation
- ESD classification testing is done to JEDEC Standard JESD22. Protection exceeds 2000 V to HBM per method A114.

DESCRIPTION

The PCK2002PL is a 1–4 fanout buffer used as a high-performance, low skew, general purpose and PCI-X clock buffer. It distributes one input clock (BUF_IN) signal to four output clocks (BUF_OUT_n).

QUICK REFERENCE DATA

BUF_IN 1 OE 2 BUF_OUT0 3 V _{SS} 4 BUF_OUT1 BUF_OUT1 BUF_OUT1 BUF_OUT1 BUF_OUT1 BUF_OUT1 BUF_OUT1
TOP VIEW SA00569

PIN DESCRIPTION

PIN CONFIGURATION

PIN NUMBER	I/O TYPE	SYMBOL	FUNCTION
1	Input	BUF_IN	Buffered clock input
3, 5, 7, 8	Output	BUF_OUT (0-3)	Buffered clock outputs
6	Input	V _{DD}	3.3 V supply
2	Input	OE	Output Enable
4	Input	V _{SS}	Ground

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay BUF_IN to BUF_OUT _n	V _{CC} = 3.3 V, C _L = 25 pF	2.9 2.8	ns
t _r	Rise time	V_{CC} = 3.3 V, C_L = 10 pF, 0.2V_{DD} to 0.6V_{DD}	450	ps
t _f	Fall time	V_{CC} = 3.3 V, C_L = 10 pF, 0.6V_{DD} to 0.2V_{DD}	400	ps
I _{CC}	Total supply current	$V_{CC} = 3.6 V$	50	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DRAWING NUMBER	
8-Pin Plastic TSSOP	–40 to +85 °C	PCK2002PLPW	SOT530-1	

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FUNCTION TABLE

OE	BUF_IN	BUF_OUTn
L	Х	L
Н	L	L
Н	Н	Н

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to V_{SS} ($V_{SS} = 0$ V).

SYMBOL	DADAMETED	CONDITION	LIN	UNIT	
STMBOL	PARAMETER	CONDITION	MIN	MAX	
V _{DD}	DC 3.3 V supply voltage		-0.5	+4.3	V
I _{IK}	DC input diode current	V ₁ < 0	—	-50	mA
VI	DC input voltage	Note 2	-0.5	V _{DD} + 0.5	V
I _{OK}	DC output diode current	current $V_{O} > V_{DD}$ or $V_{O} < 0$		±50	mA
Vo	DC output voltage	Note 2	-0.5	V _{DD} + 0.5	V
Ι _Ο	DC output source or sink current	$V_{O} \ge 0$ to V_{DD}	—	±50	mA
T _{stg}	Storage temperature range		-65	+150	°C
P _{tot}	Power dissipation per package plastic medium-shrink SO (SSOP)	For temperature range: 0 to +70 °C above +55 °C derate linearly with 11.3 mW/K	_	850	mW

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STWBUL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V _{DD}	DC 3.3V supply voltage		3.0	3.6	V
CL	Capacitive load		20	30	pF
VI	DC input voltage range		0	V _{DD}	V
Vo	DC output voltage range		0	V _{DD}	V
T _{amb}	Operating ambient temperature range in free air		-40	+85	°C

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DC CHARACTERISTICS

			TEST CONDITIONS	LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS			T _{amb} = −40 to +85 °C		
		V _{DD} (V)	OTHER		MIN	MAX	
V _{IH}	HIGH level input voltage	3.0 to 3.6	—	-	2.0	V _{DD} + 0.3	V
V _{IL}	LOW level input voltage	3.0 to 3.6	—	—	$V_{SS} - 0.3$	0.8	V
		3.0 to 3.6	I _{OH} = -1 mA	—	V _{DD} - 0.2	—	V
V _{OH}	Output HIGH voltage	3.0	I _{OH} = -24 mA	—	2.0	—	V
		3.0	I _{OH} = -12 mA	—	2.4	—	V
	Output LOW voltage	3.0 to 3.6	I _{OL} = 1 mA	—	—	0.2	V
V _{OL}		3.0	I _{OL} = 24 mA	—	—	0.8	V
		3.0	I _{OL} = 12 mA	—	—	0.55	V
		3.0	V _{OUT} = 1 V	—	-50	_	mA
ЮН	Output HIGH current	3.3	V _{OUT} = 1.65 V	—	—	-150	mA
	Output LOW current	3.0	V _{OUT} = 2.0 V	—	60	_	mA
IOL		3.3	V _{OUT} = 1.65 V	—	—	150	mA
±l	Input leakage current	3.6	$V_{I} = V_{DD}$ or GND	—	—	±5	μΑ
I _{CC}	Quiescent supply current	3.6	$V_{I} = V_{DD}$ or GND	l _O = 0	_	100	μΑ

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AC CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS		LIMITS T _{amb} = -40 to +85 °C			UNIT
			NOTES	MIN	TYP ⁶	MAX	
Т _Н	CLK HIGH time	66 MHz	2	6.0	—	—	ns
TL	CLK LOW time		3	6.0	—	—	ns
Т _Н	CLK HIGH time	140 MHz	2	2.9	—	—	ns
TL	CLK LOW time	140 MHZ	3	3.0	—	—	ns
T _R	Output rise slew rate		4	2.15	3.3	4.1	V/ns
T _F	Output fall slew rate			2.5	3.3	4.4	V/ns
T _{PLH}	Buffer LH propagation delay		5	1.8	2.9	3.4	ns
T _{PHL}	Buffer HL propagation delay		5	1.8	2.8	3.4	ns
Т _{SKW}	Bus CLK skew		1	_	_	200	ps
T _{DDSKW}	Device to device skew		1	_	_	500	ps

NOTES:

1. CLK skew is only valid for equal loading of all outputs.

2. T_H is measured at 0.5 V_{DD} as shown in Figure 2. 3. T_L is measured at 0.35 V_{DD} as shown in Figure 2. 4. T_R and T_F are measured as a transition through the threshold region 0.2 V_{DD} to 0.6 V_{DD} and 0.6 V_{DD} to 0.2 V_{DD} . 5. Input edge rate for these tests must be faster than 1 V/ns.

6. All typical values are at $V_{CC} = 3.3$ V and $T_{amb} = 25$ °C.

AC WAVEFORMS

 $V_M = 50\% V_{DD}$

 $C_{L}^{...} = 10 \text{ pF}$

 V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

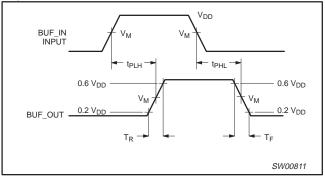


Figure 1. Load circuitry for switching times.

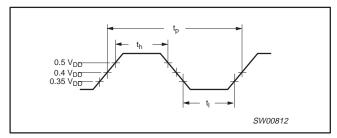


Figure 2. Buffer Output clock

TEST CIRCUIT

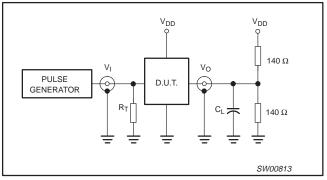
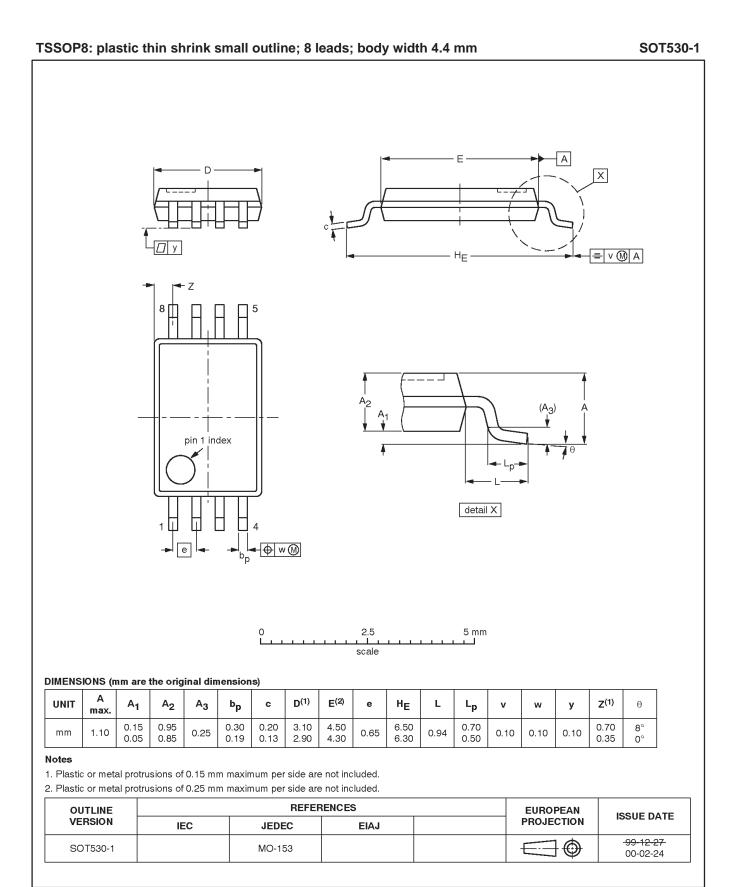


Figure 3. Load circuitry for switching times

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REVISION HISTORY

Rev	Date	Description
_3	2002 Oct 10	Product data (9397 750 10537); third version supersedes Product data second version, 2002 Mar 15. Engineering Change Notice: 853-2243 29056 (2002 Oct 09). Modifications:
		Update and change to Operating Frequency values.
_2	2002 Mar 15	Product data, second version Engineering Change Notice: 853-2256 27859 (date: 2002 Mar 15).

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Product data

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
111	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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